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What is "[Embedded - Microcontrollers](#)"?

"[Embedded - Microcontrollers](#)" refer to small, integrated circuits designed to perform specific tasks within larger systems. These microcontrollers are essentially compact computers on a single chip, containing a processor core, memory, and programmable input/output peripherals. They are called "embedded" because they are embedded within electronic devices to control various functions, rather than serving as standalone computers. Microcontrollers are crucial in modern electronics, providing the intelligence and control needed for a wide range of applications.

Applications of "[Embedded - Microcontrollers](#)"

Details

Product Status	Active
Core Processor	MIPS32® M4K™
Core Size	32-Bit Single-Core
Speed	40MHz
Connectivity	I ² C, IrDA, LINbus, PMP, SPI, UART/USART
Peripherals	Brown-out Detect/Reset, POR, PWM, WDT
Number of I/O	53
Program Memory Size	64KB (64K x 8)
Program Memory Type	FLASH
EEPROM Size	-
RAM Size	16K x 8
Voltage - Supply (Vcc/Vdd)	2.3V ~ 3.6V
Data Converters	A/D 16x10b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 105°C (TA)
Mounting Type	Surface Mount
Package / Case	64-VQFN Exposed Pad
Supplier Device Package	64-VQFN (9x9)
Purchase URL	https://www.e-xfl.com/product-detail/microchip-technology/pic32mx320f064h-40v-mr

PIC32MX3XX/4XX

High-Performance, General Purpose and USB 32-bit Flash Microcontrollers

High-Performance 32-bit RISC CPU:

- MIPS32® M4K® 32-bit core with 5-stage pipeline
- 80 MHz maximum frequency
- 1.56 DMIPS/MHz (Dhrystone 2.1) performance at 0 wait state Flash access
- Single-cycle multiply and high-performance divide unit
- MIPS16e® mode for up to 40% smaller code size
- Two sets of 32 core register files (32-bit) to reduce interrupt latency
- Prefetch Cache module to speed execution from Flash

Microcontroller Features:

- Operating temperature range of -40°C to +105°C
- Operating voltage range of 2.3V to 3.6V
- 32K to 512K Flash memory (plus an additional 12 KB of boot Flash)
- 8K to 32K SRAM memory
- Pin-compatible with most PIC24/dsPIC® DSC devices
- Multiple power management modes
- Multiple interrupt vectors with individually programmable priority
- Fail-Safe Clock Monitor Mode
- Configurable Watchdog Timer with on-chip Low-Power RC Oscillator for reliable operation

Peripheral Features:

- Atomic SET, CLEAR and INVERT operation on select peripheral registers
- Up to 4-channel hardware DMA with automatic data size detection
- USB 2.0-compliant full-speed device and On-The-Go (OTG) controller
- USB has a dedicated DMA channel
- 3 MHz to 25 MHz crystal oscillator
- Internal 8 MHz and 32 kHz oscillators

- Separate PLLs for CPU and USB clocks
- Two I²C™ modules
- Two UART modules with:
 - RS-232, RS-485 and LIN support
 - IrDA® with on-chip hardware encoder and decoder
- Up to two SPI modules
- Parallel Master and Slave Port (PMP/PSP) with 8-bit and 16-bit data and up to 16 address lines
- Hardware Real-Time Clock and Calendar (RTCC)
- Five 16-bit Timers/Counters (two 16-bit pairs combine to create two 32-bit timers)
- Five capture inputs
- Five compare/PWM outputs
- Five external interrupt pins
- High-Speed I/O pins capable of toggling at up to 80 MHz
- High-current sink/source (18 mA/18 mA) on all I/O pins
- Configurable open-drain output on digital I/O pins

Debug Features:

- Two programming and debugging Interfaces:
 - 2-wire interface with unintrusive access and real-time data exchange with application
 - 4-wire MIPS® standard enhanced JTAG interface
- Unintrusive hardware-based instruction trace
- IEEE Standard 1149.2-compatible (JTAG) boundary scan

Analog Features:

- Up to 16-channel 10-bit Analog-to-Digital Converter:
 - 1000 ksps conversion rate
 - Conversion available during Sleep, Idle
- Two Analog Comparators

PIC32MX3XX/4XX

TABLE 1: PIC32MX GENERAL PURPOSE – FEATURES

GENERAL PURPOSE														
Device	Pins	Packages ⁽²⁾	MHz	Program Memory (KB)	Data Memory (KB)	Timers/Capture/Compare	Programmable DMA Channels	VREG	Trace	EUART/SPI/I ² C™	10-bit ADC (ch)	Comparators	PMP/PSP	JTAG
PIC32MX320F032H	64	PT, MR	40	32 + 12 ⁽¹⁾	8	5/5/5	0	Yes	No	2/2/2	16	2	Yes	Yes
PIC32MX320F064H	64	PT, MR	80	64 + 12 ⁽¹⁾	16	5/5/5	0	Yes	No	2/2/2	16	2	Yes	Yes
PIC32MX320F128H	64	PT, MR	80	128 + 12 ⁽¹⁾	16	5/5/5	0	Yes	No	2/2/2	16	2	Yes	Yes
PIC32MX340F128H	64	PT, MR	80	128 + 12 ⁽¹⁾	32	5/5/5	4	Yes	No	2/2/2	16	2	Yes	Yes
PIC32MX340F256H	64	PT, MR	80	256 + 12 ⁽¹⁾	32	5/5/5	4	Yes	No	2/2/2	16	2	Yes	Yes
PIC32MX340F512H	64	PT, MR	80	512 + 12 ⁽¹⁾	32	5/5/5	4	Yes	No	2/2/2	16	2	Yes	Yes
PIC32MX320F128L	100	PT	80	128 + 12 ⁽¹⁾	16	5/5/5	0	Yes	No	2/2/2	16	2	Yes	Yes
	121	BG												
PIC32MX340F128L	100	PT	80	128 + 12 ⁽¹⁾	32	5/5/5	4	Yes	No	2/2/2	16	2	Yes	Yes
	121	BG												
PIC32MX360F256L	100	PT	80	256 + 12 ⁽¹⁾	32	5/5/5	4	Yes	Yes	2/2/2	16	2	Yes	Yes
	121	BG												
PIC32MX360F512L	100	PT	80	512 + 12 ⁽¹⁾	32	5/5/5	4	Yes	Yes	2/2/2	16	2	Yes	Yes
	121	BG												

Legend: PT = TQFP MR = QFN BG = XBGA

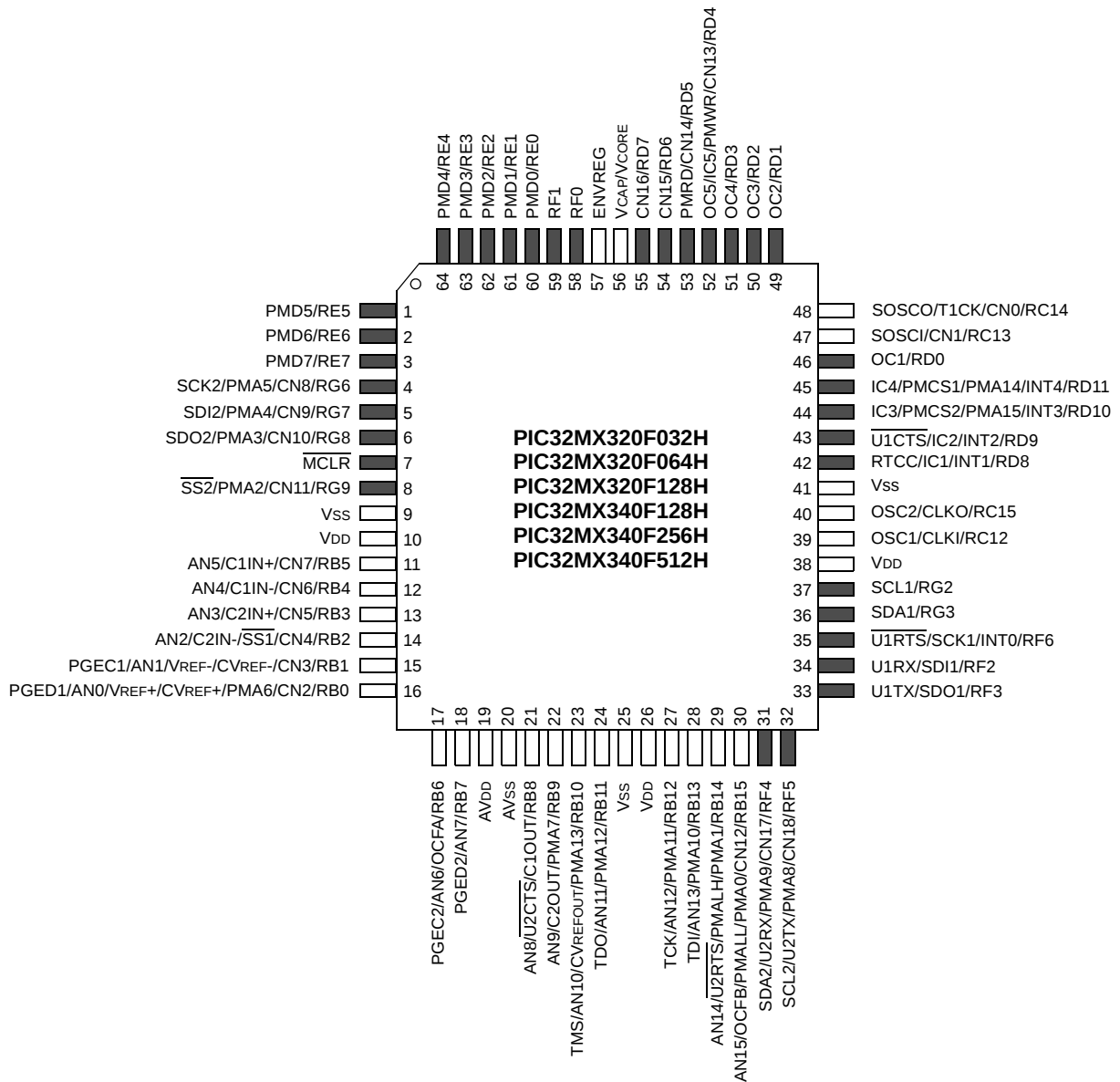
Note 1: This device features 12 KB Boot Flash memory.

2: See Legend for an explanation of the acronyms. See **Section 30.0 “Packaging Information”** for details.

Pin Diagrams (Continued)

64-Pin TQFP (General Purpose)

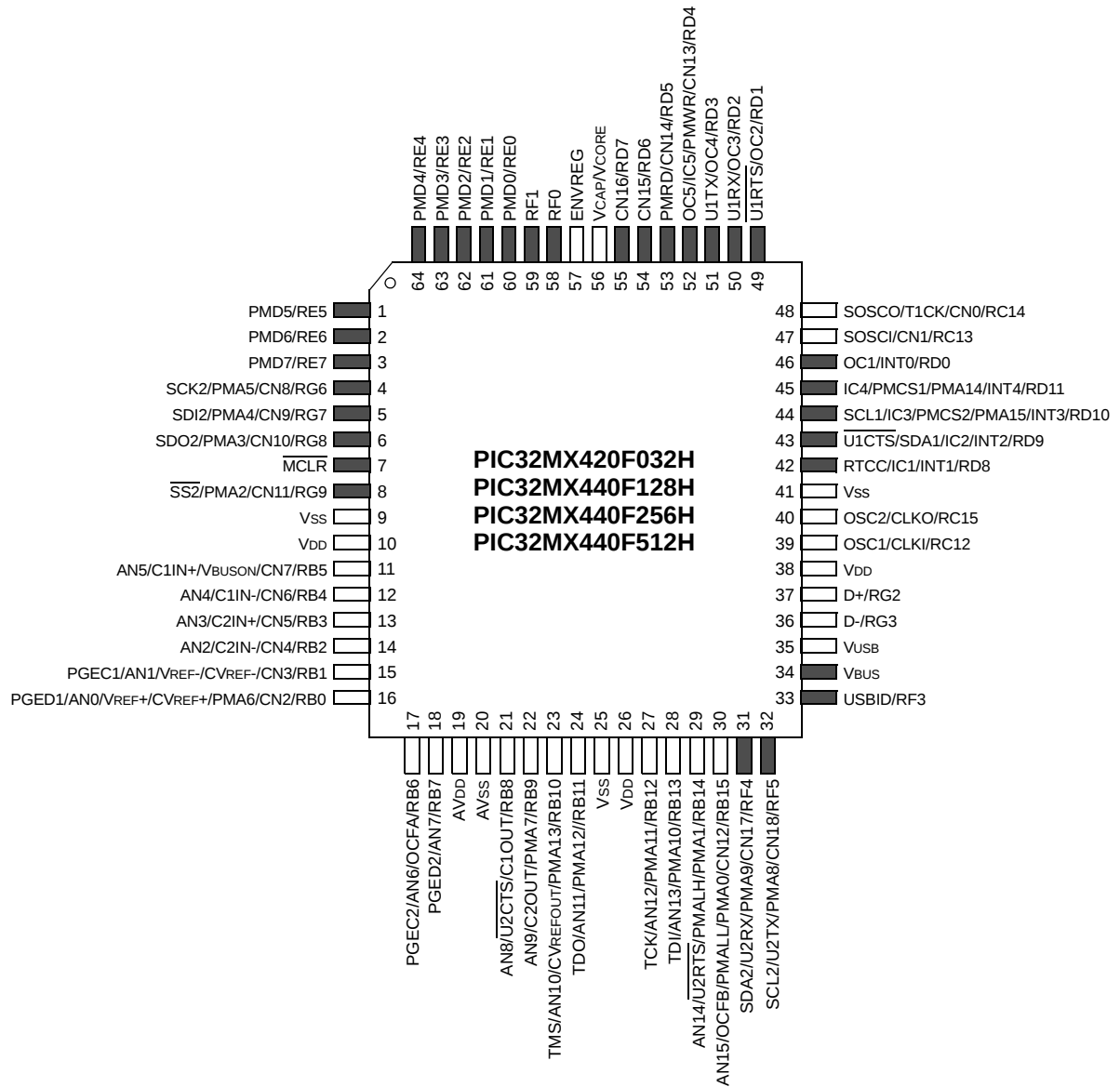
■ = Pins are up to 5V tolerant



Pin Diagrams (Continued)

64-Pin TQFP (USB)

■ = Pins are up to 5V tolerant



PIC32MX3XX/4XX

FIGURE 4-3: MEMORY MAP ON RESET FOR PIC32MX320F128H AND PIC32MX320F128L DEVICES⁽¹⁾

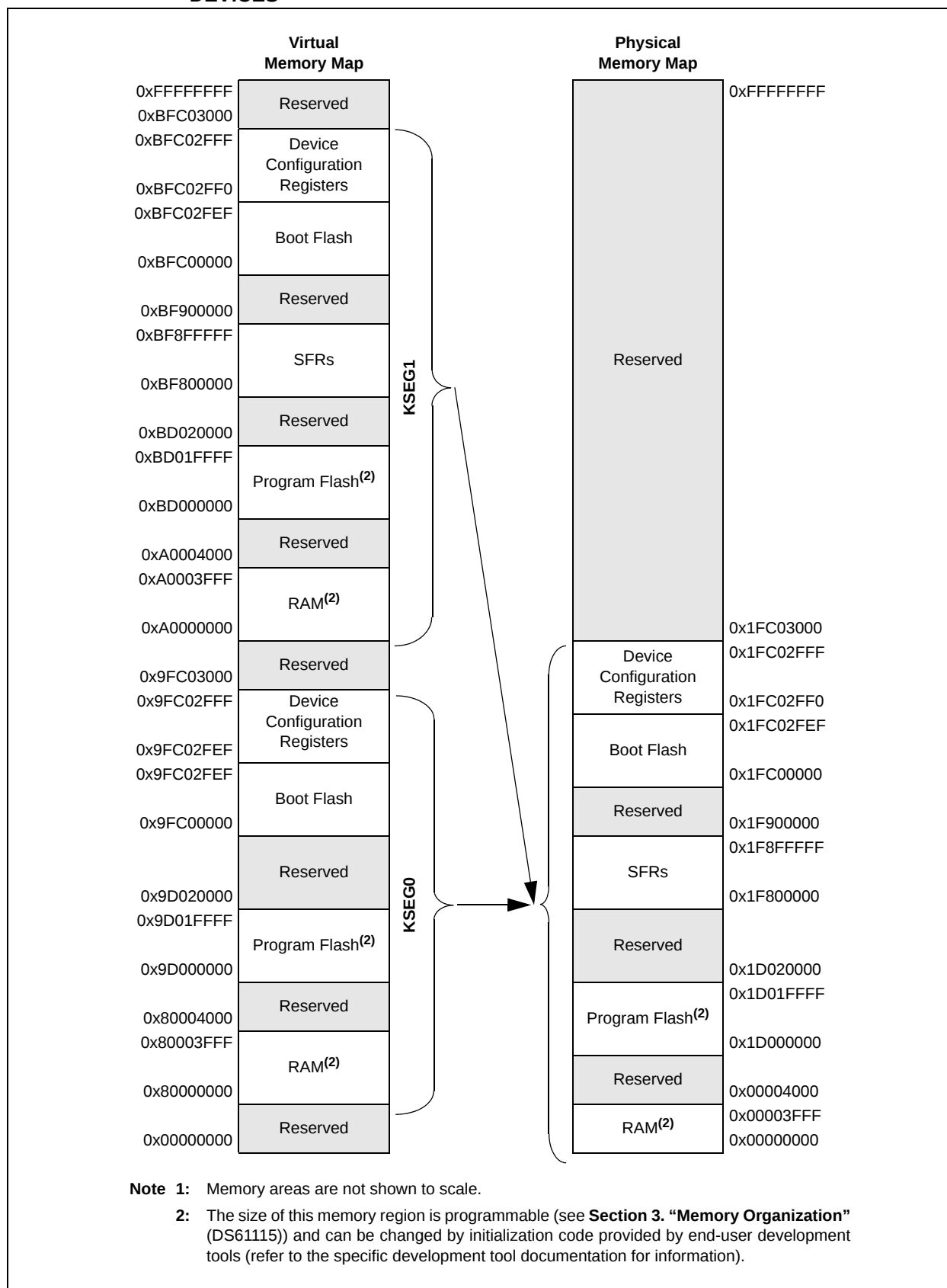


TABLE 4-3: INTERRUPT REGISTERS MAP FOR PIC32MX340F128H, PIC32MX340F256H, PIC32MX340F512H, PIC32MX340F128L, PIC32MX360F256L AND PIC32MX360F512L DEVICES ONLY⁽¹⁾

Virtual Address (BF88..#)	Register Name	Bit Range	Bits																All Resets	
			31/15	30/14	29/13	28/12	27/11	26/10	25/9	24/8	23/7	22/6	21/5	20/4	19/3	18/2	17/1	16/0		
1000	INTCON	31:16	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	SS0	0000	
		15:0	—	—	—	MVEC	—	TPC<2:0>			—	—	—	INT4EP	INT3EP	INT2EP	INT1EP	INT0EP	0000	
1010	INTSTAT ⁽²⁾	31:16	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	0000	
		15:0	—	—	—	—	—	SRIPL<2:0>			—	—	VEC<5:0>						0000	
1020	IPTMR	31:16	IPTMR<31:0>																0000	
		15:0																	0000	
1030	IFS0	31:16	I2C1MIF	I2C1SIF	I2C1BIF	U1TXIF	U1RXIF	U1EIF	SPI1RXIF	SPI1TXIF	SPI1EIF	OC5IF	IC5IF	T5IF	INT4IF	OC4IF	IC4IF	T4IF	0000	
		15:0	INT3IF	OC3IF	IC3IF	T3IF	INT2IF	OC2IF	IC2IF	T2IF	INT1IF	OC1IF	IC1IF	T1IF	INT0IF	CS1IF	CS0IF	CTIF	0000	
1040	IFS1	31:16	—	—	—	—	—	—	—	FCEIF	—	—	—	—	DMA3IF	DMA2IF	DMA1IF	DMA0IF	0000	
		15:0	RTCCIF	FSCMIF	I2C2MIF	I2C2SIF	I2C2BIF	U2TXIF	U2RXIF	U2EIF	SPI2RXIF	SPI2TXIF	SPI2EIF	CMP2IF	CMP1IF	PMPIF	AD1IF	CNIF	0000	
1060	IEC0	31:16	I2C1MIE	I2C1SIE	I2C1BIE	U1TXIE	U1RXIE	U1EIE	SPI1RXIE	SPI1TXIE	SPI1EIE	OC5IE	IC5IE	T5IE	INT4IE	OC4IE	IC4IE	T4IE	0000	
		15:0	INT3IE	OC3IE	IC3IE	T3IE	INT2IE	OC2IE	IC2IE	T2IE	INT1IE	OC1IE	IC1IE	T1IE	INT0IE	CS1IE	CS0IE	CTIE	0000	
1070	IEC1	31:16	—	—	—	—	—	—	—	FCEIE	—	—	—	—	DMA3IE	DMA2IE	DMA1IE	DMA0IE	0000	
		15:0	RTCCIE	FSCMIE	I2C2MIE	—	—	—	—	—	SPI2RXIE	SPI2TXIE	SPI2EIE	CMP2IE	CMP1IE	PMPIE	AD1IE	CNIE	0000	
1090	IPC0	31:16	—	—	—	INT0IP<2:0>			INT0IS<1:0>			—	—	—	CS1IP<2:0>			CS1IS<1:0>		0000
		15:0	—	—	—	CS0IP<2:0>			CS0IS<1:0>			—	—	—	CTIP<2:0>			CTIS<1:0>		0000
10A0	IPC1	31:16	—	—	—	INT1IP<2:0>			INT1IS<1:0>			—	—	—	OC1IP<2:0>			OC1IS<1:0>		0000
		15:0	—	—	—	IC1IP<2:0>			IC1IS<1:0>			—	—	—	T1IP<2:0>			T1IS<1:0>		0000
10B0	IPC2	31:16	—	—	—	INT2IP<2:0>			INT2IS<1:0>			—	—	—	OC2IP<2:0>			OC2IS<1:0>		0000
		15:0	—	—	—	IC2IP<2:0>			IC2IS<1:0>			—	—	—	T2IP<2:0>			T2IS<1:0>		0000
10C0	IPC3	31:16	—	—	—	INT3IP<2:0>			INT3IS<1:0>			—	—	—	OC3IP<2:0>			OC3IS<1:0>		0000
		15:0	—	—	—	IC3IP<2:0>			IC3IS<1:0>			—	—	—	T3IP<2:0>			T3IS<1:0>		0000
10D0	IPC4	31:16	—	—	—	INT4IP<2:0>			INT4IS<1:0>			—	—	—	OC4IP<2:0>			OC4IS<1:0>		0000
		15:0	—	—	—	IC4IP<2:0>			IC4IS<1:0>			—	—	—	T4IP<2:0>			T4IS<1:0>		0000
10E0	IPC5	31:16	—	—	—	SPI1IP<2:0>			SPI1IS<1:0>			—	—	—	OC5IP<2:0>			OC5IS<1:0>		0000
		15:0	—	—	—	IC5IP<2:0>			IC5IS<1:0>			—	—	—	T5IP<2:0>			T5IS<1:0>		0000
10F0	IPC6	31:16	—	—	—	AD1IP<2:0>			AD1IS<1:0>			—	—	—	CNIP<2:0>			CNIS<1:0>		0000
		15:0	—	—	—	I2C1IP<2:0>			I2C1IS<1:0>			—	—	—	U1IP<2:0>			U1IS<1:0>		0000
1100	IPC7	31:16	—	—	—	SPI2IP<2:0>			SPI2IS<1:0>			—	—	—	CMP2IP<2:0>			CMP2IS<1:0>		0000
		15:0	—	—	—	CMP1IP<2:0>			CMP1IS<1:0>			—	—	—	PMPIP<2:0>			PMPIS<1:0>		0000
1110	IPC8	31:16	—	—	—	RTCCIP<2:0>			RTCCIS<1:0>			—	—	—	FSCMIP<2:0>			FSCMIS<1:0>		0000
		15:0	—	—	—	I2C2IP<2:0>			I2C2IS<1:0>			—	—	—	U2IP<2:0>			U2IS<1:0>		0000
1120	IPC9	31:16	—	—	—	DMA3IP<2:0>			DMA3IS<1:0>			—	—	—	DMA2IP<2:0>			DMA2IS<1:0>		0000
		15:0	—	—	—	DMA1IP<2:0>			DMA1IS<1:0>			—	—	—	DMA0IP<2:0>			DMA0IS<1:0>		0000
1140	IPC11	31:16	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	0000	
		15:0	—	—	—	—	—	—	—	—	—	—	—	—	FCEIP<2:0>			FCEIS<1:0>		0000

Legend: x = unknown value on Reset, — = unimplemented, read as '0'. Reset values are shown in hexadecimal.

- Note 1:** Except where noted, all registers in this table have corresponding CLR, SET and INV registers at their virtual addresses, plus offsets of 0x4, 0x8 and 0xC, respectively. See **Section 12.1.1 “CLR, SET and INV Registers”** for more information.
- 2:** This register does not have associated CLR, SET, and INV registers.

TABLE 4-13: ADC REGISTERS MAP (CONTINUED)

Virtual Address (BF80_#)	Register Name	Bit Range	Bits																All Resets
			31/15	30/14	29/13	28/12	27/11	26/10	25/9	24/8	23/7	22/6	21/5	20/4	19/3	18/2	17/1	16/0	
9110	ADC1BUFA	31:16	ADC Result Word A (ADC1BUFA<31:0>)																0000
		15:0																	0000
9120	ADC1BUFB	31:16	ADC Result Word B (ADC1BUFB<31:0>)																0000
		15:0																	0000
9130	ADC1BUFC	31:16	ADC Result Word C (ADC1BUFC<31:0>)																0000
		15:0																	0000
9140	ADC1BUFD	31:16	ADC Result Word D (ADC1BUFD<31:0>)																0000
		15:0																	0000
9150	ADC1BUFE	31:16	ADC Result Word E (ADC1BUFE<31:0>)																0000
		15:0																	0000
9160	ADC1BUFF	31:16	ADC Result Word F (ADC1BUFF<31:0>)																0000
		15:0																	0000

Legend: x = unknown value on Reset, — = unimplemented, read as '0'. Reset values are shown in hexadecimal.
Note 1: This register has corresponding CLR, SET and INV registers at its virtual address, plus an offset of 0x4, 0x8 and 0xC, respectively. See **Section 12.1.1 “CLR, SET and INV Registers”** for more information.

TABLE 4-19: FLASH CONTROLLER REGISTERS MAP

Virtual Address (BF80_#)	Register Name	Bit Range	Bits																All Resets
			31/15	30/14	29/13	28/12	27/11	26/10	25/9	24/8	23/7	22/6	21/5	20/4	19/3	18/2	17/1	16/0	
F400	NVMCON ⁽¹⁾	31:16	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	0000	
		15:0	WR	WREN	WRERR	LVDERR	LVDSTAT	—	—	—	—	—	—	NVMOP<3:0>				0000	
F410	NVMKEY	31:16	NVMKEY<31:0>																0000
		15:0																	0000
F420	NVMADDR ⁽¹⁾	31:16	NVMADDR<31:0>																0000
		15:0																	0000
F430	NVMDATA	31:16	NVMDATA<31:0>																0000
		15:0																	0000
F440	NVMSRC ADDR	31:16	NVMSRCADDR<31:0>																0000
		15:0																	0000

Legend: x = unknown value on Reset, — = unimplemented, read as '0'. Reset values are shown in hexadecimal.

Note 1: This register has corresponding CLR, SET and INV registers at its virtual address, plus an offset of 0x4, 0x8 and 0xC, respectively. See **Section 12.1.1 “CLR, SET and INV Registers”** for more information.

TABLE 4-20: SYSTEM CONTROL REGISTERS MAP^(1,2)

Virtual Address (BF80_#)	Register Name	Bit Range	Bits																All Resets
			31/15	30/14	29/13	28/12	27/11	26/10	25/9	24/8	23/7	22/6	21/5	20/4	19/3	18/2	17/1	16/0	
F000	OSCCON	31:16	—	—	PLLODIV<2:0>			FRCDIV<2:0>			—	SOSCRDY	—	PBDIV<1:0>		PLLMULT<2:0>			0000
		15:0	—	COSC<2:0>			—	NOSC<2:0>			CLKLOCK	ULOCK	SLOCK	SLPEN	CF	UFRGEN	SOSCEN	OSWEN	0000
F010	OSCTUN	31:16	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	0000
		15:0	—	—	—	—	—	—	—	—	—	—	TUN<5:0>						0000
0000	WDTCON	31:16	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	0000
		15:0	ON	—	—	—	—	—	—	—	—	SWDTPS<4:0>					—	WDTCLR	0000
F600	RCON	31:16	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	0000
		15:0	—	—	—	—	—	—	—	CMR	VREGS	EXTR	SWR	—	WDTO	SLEEP	IDLE	BOR	POR
F610	RSWRST	31:16	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	0000
		15:0	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	SWRST
F230	SYSKEY ⁽³⁾	31:16	SYSKEY<31:0>																0000
		15:0																	0000

Legend: x = unknown value on Reset, — = unimplemented, read as '0'. Reset values are shown in hexadecimal.

Note 1: Except where noted, all registers in this table have corresponding CLR, SET and INV registers at their virtual addresses, plus offsets of 0x4, 0x8 and 0xC, respectively. See **Section 12.1.1 “CLR, SET and INV Registers”** for more information.

2: Reset values are dependent on the DEVCFGx Configuration bits and the type of reset.

3: This register does not have associated CLR, SET, and INV registers.

TABLE 4-43: USB REGISTERS MAP⁽¹⁾ (CONTINUED)

Virtual Address (BF88_#)	Register Name	Bit Range	Bits																All Resets
			31/15	30/14	29/13	28/12	27/11	26/10	25/9	24/8	23/7	22/6	21/5	20/4	19/3	18/2	17/1	16/0	
5280	U1FRML ⁽³⁾	31:16	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	0000
		15:0	—	—	—	—	—	—	—	—	FRML<7:0>								0000
5290	U1FRMH ⁽³⁾	31:16	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	0000
		15:0	—	—	—	—	—	—	—	—	—	—	—	—	FRMH<10:8>				0000
52A0	U1TOK	31:16	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	0000
		15:0	—	—	—	—	—	—	—	—	PID<3:0>				EP<3:0>				0000
52B0	U1SOF	31:16	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	0000
		15:0	—	—	—	—	—	—	—	—	CNT<7:0>								0000
52C0	U1BDTP2	31:16	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	0000
		15:0	—	—	—	—	—	—	—	—	BDTPTRH<7:0>								0000
52D0	U1BDTP3	31:16	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	0000
		15:0	—	—	—	—	—	—	—	—	BDTPTRU<7:0>								0000
52E0	U1CNFG1	31:16	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	0000
		15:0	—	—	—	—	—	—	—	—	UTEYE	UOEMON	USBFRZ	USBSIDL	—	—	—	—	0000
5300	U1EP0	31:16	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	0000
		15:0	—	—	—	—	—	—	—	—	LSPD	RETRYDIS	—	EPCONDIS	EPRXEN	EPTXEN	EPSTALL	EPHSHK	0000
5310	U1EP1	31:16	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	0000
		15:0	—	—	—	—	—	—	—	—	—	—	—	EPCONDIS	EPRXEN	EPTXEN	EPSTALL	EPHSHK	0000
5320	U1EP2	31:16	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	0000
		15:0	—	—	—	—	—	—	—	—	—	—	—	EPCONDIS	EPRXEN	EPTXEN	EPSTALL	EPHSHK	0000
5330	U1EP3	31:16	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	0000
		15:0	—	—	—	—	—	—	—	—	—	—	—	EPCONDIS	EPRXEN	EPTXEN	EPSTALL	EPHSHK	0000
5340	U1EP4	31:16	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	0000
		15:0	—	—	—	—	—	—	—	—	—	—	—	EPCONDIS	EPRXEN	EPTXEN	EPSTALL	EPHSHK	0000
5350	U1EP5	31:16	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	0000
		15:0	—	—	—	—	—	—	—	—	—	—	—	EPCONDIS	EPRXEN	EPTXEN	EPSTALL	EPHSHK	0000
5360	U1EP6	31:16	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	0000
		15:0	—	—	—	—	—	—	—	—	—	—	—	EPCONDIS	EPRXEN	EPTXEN	EPSTALL	EPHSHK	0000
5370	U1EP7	31:16	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	0000
		15:0	—	—	—	—	—	—	—	—	—	—	—	EPCONDIS	EPRXEN	EPTXEN	EPSTALL	EPHSHK	0000

Legend: x = unknown value on Reset, — = unimplemented, read as '0'. Reset values are shown in hexadecimal.

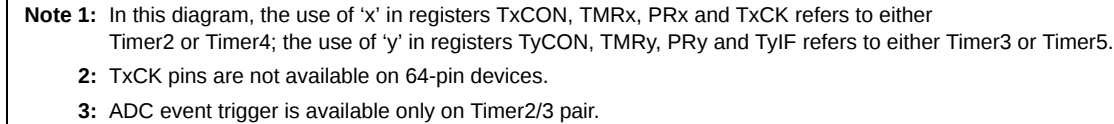
Note 1: Except where noted, all registers in this table have corresponding CLR, SET and INV registers at their virtual addresses, plus offsets of 0x4, 0x8 and 0xC, respectively. See **Section 12.1.1 "CLR, SET and INV Registers"** for more information.

2: This register does not have associated CLR, SET, and INV registers.

3: All bits in this register are read-only; therefore, CLR, SET, and INV registers are not supported.

4: The reset value for this bit is undefined.

--



25.0 POWER-SAVING FEATURES

Note 1: This data sheet summarizes the features of the PIC32MX3XX/4XX family of devices. It is not intended to be a comprehensive reference source. To complement the information in this data sheet, refer to **Section 10. “Power-Saving Features”** (DS61130) of the “PIC32 Family Reference Manual”, which is available from the Microchip web site (www.microchip.com/PIC32).

2: Some registers and associated bits described in this section may not be available on all devices. Refer to **Section 4.0 “Memory Organization”** in this data sheet for device-specific register and bit information.

This section describes power-saving for the PIC32MX3XX/4XX. The PIC32MX devices offer a total of nine methods and modes that are organized into two categories that allow the user to balance power consumption with device performance. In all of the methods and modes described in this section, power-saving is controlled by software.

25.1 Power-Saving with CPU Running

When the CPU is running, power consumption can be controlled by reducing the CPU clock frequency, lowering the PBCLK, and by individually disabling modules. These methods are grouped into the following modes:

- FRC Run mode: the CPU is clocked from the FRC clock source with or without postscalers.
- LPRC Run mode: the CPU is clocked from the LPRC clock source.
- Sosc Run mode: the CPU is clocked from the Sosc clock source.
- Peripheral Bus Scaling mode: peripherals are clocked at programmable fraction of the CPU clock (SYSCLK).

25.2 CPU Halted Methods

The device supports two power-saving modes, Sleep and Idle, both of which halt the clock to the CPU. These modes operate with all clock sources, as listed below:

- Posc Idle Mode: the system clock is derived from the Posc. The system clock source continues to operate.
Peripherals continue to operate, but can optionally be individually disabled.
- FRC Idle Mode: the system clock is derived from the FRC with or without postscalers. Peripherals continue to operate, but can optionally be individually disabled.
- Sosc Idle Mode: the system clock is derived from the Sosc. Peripherals continue to operate, but can optionally be individually disabled.

- LPRC Idle Mode: the system clock is derived from the LPRC.

Peripherals continue to operate, but can optionally be individually disabled. This is the lowest power mode for the device with a clock running.

- Sleep Mode: the CPU, the system clock source, and any peripherals that operate from the system clock source, are halted.

Some peripherals can operate in Sleep using specific clock sources. This is the lowest power mode for the device.

25.3 Power-Saving Operation

The purpose of all power-saving is to reduce power consumption by reducing the device clock frequency. To achieve this, low-frequency clock sources can be selected. In addition, the peripherals and CPU can be halted or disabled to further reduce power consumption.

25.3.1 SLEEP MODE

Sleep mode has the lowest power consumption of the device Power-Saving operating modes. The CPU and most peripherals are halted. Select peripherals can continue to operate in Sleep mode and can be used to wake the device from Sleep. See the individual peripheral module sections for descriptions of behavior in Sleep mode.

Sleep mode includes the following characteristics:

- The CPU is halted.
- The system clock source is typically shut down. See **Section 25.3.2 “Idle Mode”** for specific information.
- There can be a wake-up delay based on the oscillator selection.
- The Fail-Safe Clock Monitor (FSCM) does not operate during Sleep mode.
- The BOR circuit, if enabled, remains operative during Sleep mode.
- The WDT, if enabled, is not automatically cleared prior to entering Sleep mode.
- Some peripherals can continue to operate in Sleep mode. These peripherals include I/O pins that detect a change in the input signal, WDT, ADC, UART and peripherals that use an external clock input or the internal LPRC oscillator, e.g., RTCC and Timer 1.
- I/O pins continue to sink or source current in the same manner as they do when the device is not in Sleep.
- The USB module can override the disabling of the Posc or FRC. Refer to **Section 11.0 “USB On-The-Go (OTG)”** for specific details.
- Some modules can be individually disabled by software prior to entering Sleep in order to further reduce consumption.

REGISTER 26-3: DEVCFG2: DEVICE CONFIGURATION WORD 2

Bit Range	Bit 31/23/15/7	Bit 30/22/14/6	Bit 29/21/13/5	Bit 28/20/12/4	Bit 27/19/11/3	Bit 26/18/10/2	Bit 25/17/9/1	Bit 24/16/8/0
31:24	r-1	r-1	r-1	r-1	r-1	r-1	r-1	r-1
	—	—	—	—	—	—	—	—
23:16	r-1	r-1	r-1	r-1	r-1	R/P	R/P	R/P
	—	—	—	—	—	FPLLIDIV<2:0>		
15:8	R/P	r-1	r-1	r-1	r-1	R/P	R/P	R/P
	UPLLEN	—	—	—	—	UPLLIDIV<2:0>		
7:0	r-1	R/P	R/P	R/P	r-1	R/P	R/P	R/P
	—	FPLLMUL<2:0>			—	FPLLIDIV<2:0>		

Legend:

R = Readable bit W = Writable bit P = Programmable bit r = Reserved bit
U = Unimplemented bit -n = Bit Value at POR: ('0', '1', x = Unknown)

bit 31-19 **Reserved:** Write '1'

bit 18-16 **FPLLIDIV<2:0>:** Default Postscaler for PLL bits

111 = PLL output divided by 256
110 = PLL output divided by 64
101 = PLL output divided by 32
100 = PLL output divided by 16
011 = PLL output divided by 8
010 = PLL output divided by 4
001 = PLL output divided by 2
000 = PLL output divided by 1

bit 15 **UPLLEN:** USB PLL Enable bit
1 = Disable and bypass USB PLL
0 = Enable USB PLL

bit 14-11 **Reserved:** Write '1'

bit 10-8 **UPLLIDIV<2:0>:** PLL Input Divider bits

111 = 12x divider
110 = 10x divider
101 = 6x divider
100 = 5x divider
011 = 4x divider
010 = 3x divider
010 = 3x divider
001 = 2x divider
000 = 1x divider

bit 7 **Reserved:** Write '1'

bit 6-4 **FPLLMUL<2:0>:** PLL Multiplier bits

111 = 24x multiplier
110 = 21x multiplier
101 = 20x multiplier
100 = 19x multiplier
011 = 18x multiplier
010 = 17x multiplier
001 = 16x multiplier
000 = 15x multiplier

bit 3 **Reserved:** Write '1'

bit 2-0 **FPLLIDIV<2:0>:** PLL Input Divider bits

111 = 12x divider
110 = 10x divider
101 = 6x divider
100 = 5x divider
011 = 4x divider
010 = 3x divider
001 = 2x divider
000 = 1x divider

TABLE 27-1: MIPS32® INSTRUCTION SET (CONTINUED)

Instruction	Description	Function
TGE	Trap if Greater Than or Equal	if (int)Rs >= (int)Rt TrapException
TGEI	Trap if Greater Than or Equal Immediate	if (int)Rs >= (int)Immed TrapException
TGEIU	Trap if Greater Than or Equal Immediate Unsigned	if (uns)Rs >= (uns)Immed TrapException
TGEU	Trap if Greater Than or Equal Unsigned	if (uns)Rs >= (uns)Rt TrapException
TLT	Trap if Less Than	if (int)Rs < (int)Rt TrapException
TLTI	Trap if Less Than Immediate	if (int)Rs < (int)Immed TrapException
TLTIU	Trap if Less Than Immediate Unsigned	if (uns)Rs < (uns)Immed TrapException
TLTU	Trap if Less Than Unsigned	if (uns)Rs < (uns)Rt TrapException
TNE	Trap if Not Equal	if Rs != Rt TrapException
TNEI	Trap if Not Equal Immediate	if Rs != (int)Immed TrapException
WAIT	Wait for Interrupt	Go to a low power mode and stall until interrupt occurs
WRPGPR	Write to GPR in Previous Shadow Set	SGPR[SRSCtl _{PSS} , Rd] = Rt
WSBH	Word Swap Bytes Within Halfwords	Rd = Rt _{23..16} Rt _{31..24} Rt _{7..0} Rt _{15..8}
XOR	Exclusive OR	Rd = Rs ^ Rt
XORI	Exclusive OR Immediate	Rt = Rs ^ (uns)Immed

Note 1: This instruction is deprecated and should not be used.

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FIGURE 29-5: EXTERNAL RESET TIMING CHARACTERISTICS

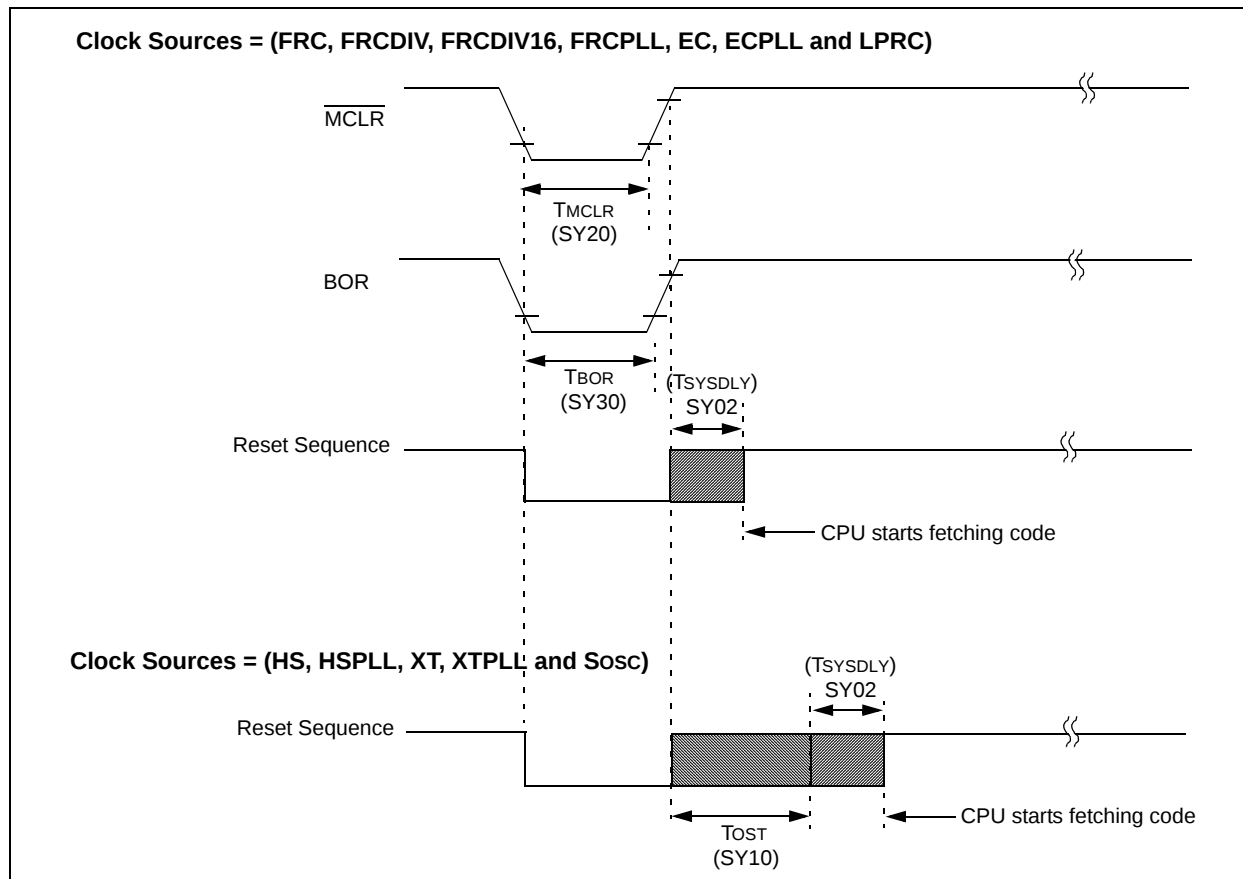


TABLE 29-22: RESETS TIMING

AC CHARACTERISTICS			Standard Operating Conditions: 2.3V to 3.6V (unless otherwise stated) Operating temperature -40°C ≤ TA ≤ +85°C for Industrial -40°C ≤ TA ≤ +105°C for V-Temp				
Param. No.	Symbol	Characteristics ⁽¹⁾	Min.	Typical ⁽²⁾	Max.	Units	Conditions
SY00	TPU	Power-up Period Internal Voltage Regulator Enabled	—	400	600	μs	-40°C to +85°C
SY01	TPWRT	Power-up Period External Vcore Applied (Power-Up-Timer Active)	48	64	80	ms	-40°C to +85°C
SY02	TSYSDLY	System Delay Period: Time required to reload Device Configuration Fuses plus SYSCLK delay before first instruction is fetched.	—	1 μs + 8 SYSCLK cycles	—	—	-40°C to +85°C
SY20	TMCLR	MCLR Pulse Width (low)	—	2	—	μs	-40°C to +85°C
SY30	TBOR	BOR Pulse Width (low)	—	1	—	μs	-40°C to +85°C

Note 1: These parameters are characterized, but not tested in manufacturing.

2: Data in "Typ" column is at 3.3V, 25°C unless otherwise stated. Characterized by design but not tested.

FIGURE 29-10: SPIx MODULE MASTER MODE (CKE = 0) TIMING CHARACTERISTICS

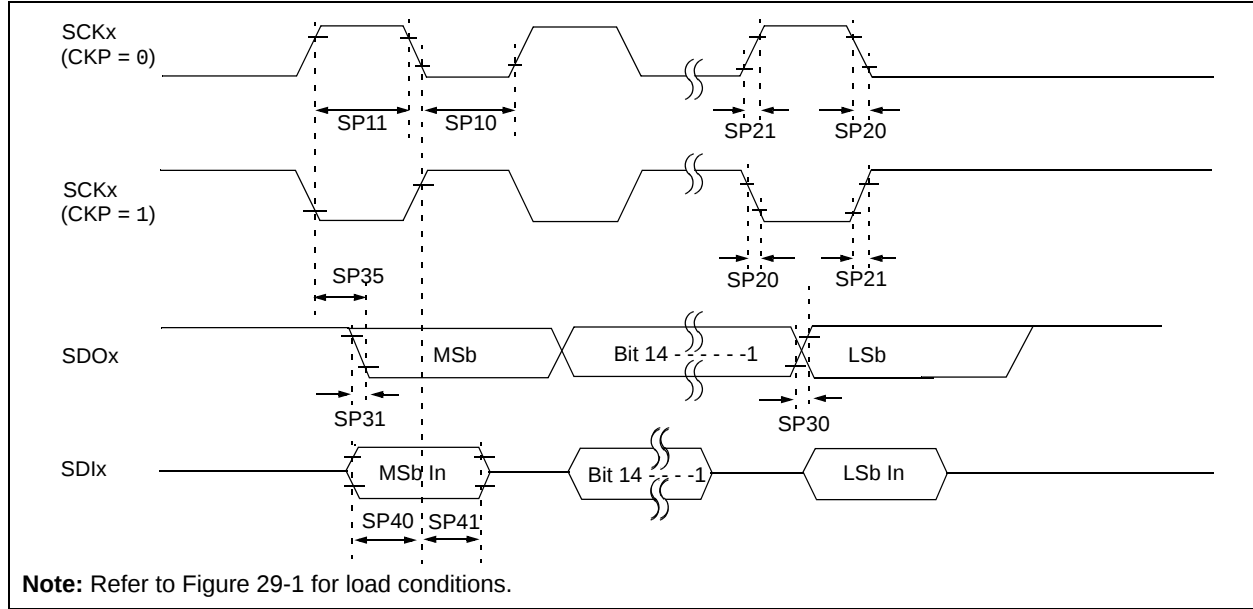


TABLE 29-28: SPIx MASTER MODE (CKE = 0) TIMING REQUIREMENTS

AC CHARACTERISTICS			Standard Operating Conditions: 2.3V to 3.6V (unless otherwise stated) Operating temperature -40°C ≤ TA ≤ +85°C for Industrial -40°C ≤ TA ≤ +105°C for V-Temp				
Param. No.	Symbol	Characteristics ⁽¹⁾	Min.	Typical ⁽²⁾	Max.	Units	Conditions
SP10	TsCL	SCKx Output Low Time ⁽³⁾	Tsck/2	—	—	ns	—
SP11	TsCH	SCKx Output High Time ⁽³⁾	Tsck/2	—	—	ns	—
SP20	TscF	SCKx Output Fall Time ⁽⁴⁾	—	—	—	ns	See parameter DO32
SP21	TscR	SCKx Output Rise Time ⁽⁴⁾	—	—	—	ns	See parameter DO31
SP30	TdoF	SDOx Data Output Fall Time ⁽⁴⁾	—	—	—	ns	See parameter DO32
SP31	TdoR	SDOx Data Output Rise Time ⁽⁴⁾	—	—	—	ns	See parameter DO31
SP35	Tsch2doV, Tscl2doV	SDOx Data Output Valid after SCKx Edge	—	—	15	ns	VDD > 2.7V
			—	—	20	ns	VDD < 2.7V
SP40	TdiV2sch, TdiV2scl	Setup Time of SDIx Data Input to SCKx Edge	10	—	—	ns	—
SP41	Tsch2diL, Tscl2diL	Hold Time of SDIx Data Input to SCKx Edge	10	—	—	ns	—

Note 1: These parameters are characterized, but not tested in manufacturing.

2: Data in “Typical” column is at 3.3V, 25°C unless otherwise stated. Parameters are for design guidance only and are not tested.

3: The minimum clock period for SCKx is 40 ns. Therefore, the clock generated in Master mode must not violate this specification.

4: Assumes 50 pF load on all SPIx pins.

FIGURE 29-16: I2Cx BUS START/STOP BITS TIMING CHARACTERISTICS (SLAVE MODE)

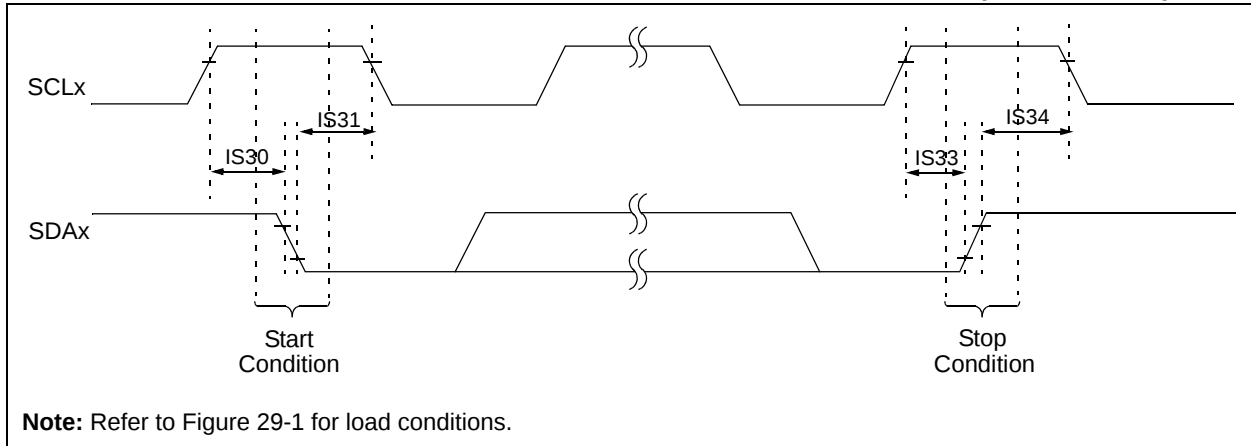
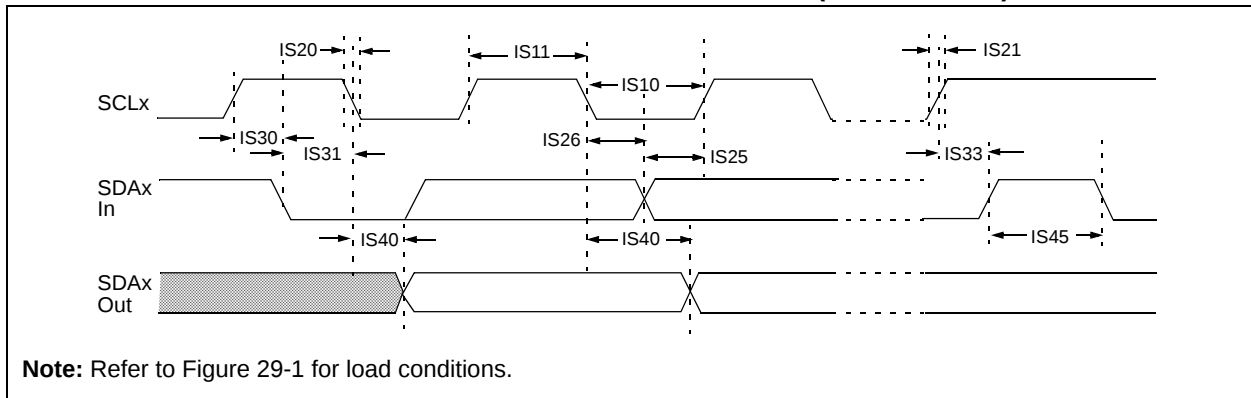


FIGURE 29-17: I2Cx BUS DATA TIMING CHARACTERISTICS (SLAVE MODE)



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TABLE 29-36: ANALOG-TO-DIGITAL CONVERSION TIMING REQUIREMENTS

AC CHARACTERISTICS			Standard Operating Conditions: 2.3V to 3.6V (unless otherwise stated) Operating temperature -40°C ≤TA ≤+85°C for Industrial -40°C ≤TA ≤+105°C for V-Temp				
Param. No.	Symbol	Characteristics	Min.	Typical ⁽¹⁾	Max.	Units	Conditions
Clock Parameters							
AD50	TAD	Analog-to-Digital Clock Period	65	—	—	ns	See Table 29-35 and Note 2
AD51	TRC	Analog-to-Digital Internal RC Oscillator Period	—	250	—	ns	See Note 3
Conversion Rate							
AD55	TCONV	Conversion Time	—	12 TAD	—	—	—
AD56	FCNV	Throughput Rate (Sampling Speed)	—	—	1000	KSPS	AVDD = 3.0V to 3.6V
			—	—	400	KSPS	AVDD = 2.5V to 3.6V
AD57	TSAMP	Sample Time	1 TAD	—	—	—	TSAMP must be ≥ 132 ns.
Timing Parameters							
AD60	TPCS	Conversion Start from Sample Trigger	—	1.0 TAD	—	—	Auto-Convert Trigger (SSRC<2:0> = 111) not selected. See Note 3
AD61	TPSS	Sample Start from Setting Sample (SAMP) bit	0.5 TAD	—	1.5 TAD	—	—
AD62	TCSS	Conversion Completion to Sample Start (ASAM = 1)	—	0.5 TAD	—	—	See Note 3
AD63	TDPU	Time to Stabilize Analog Stage from Analog-to-Digital OFF to Analog-to-Digital ON	—	—	2	μs	See Note 3

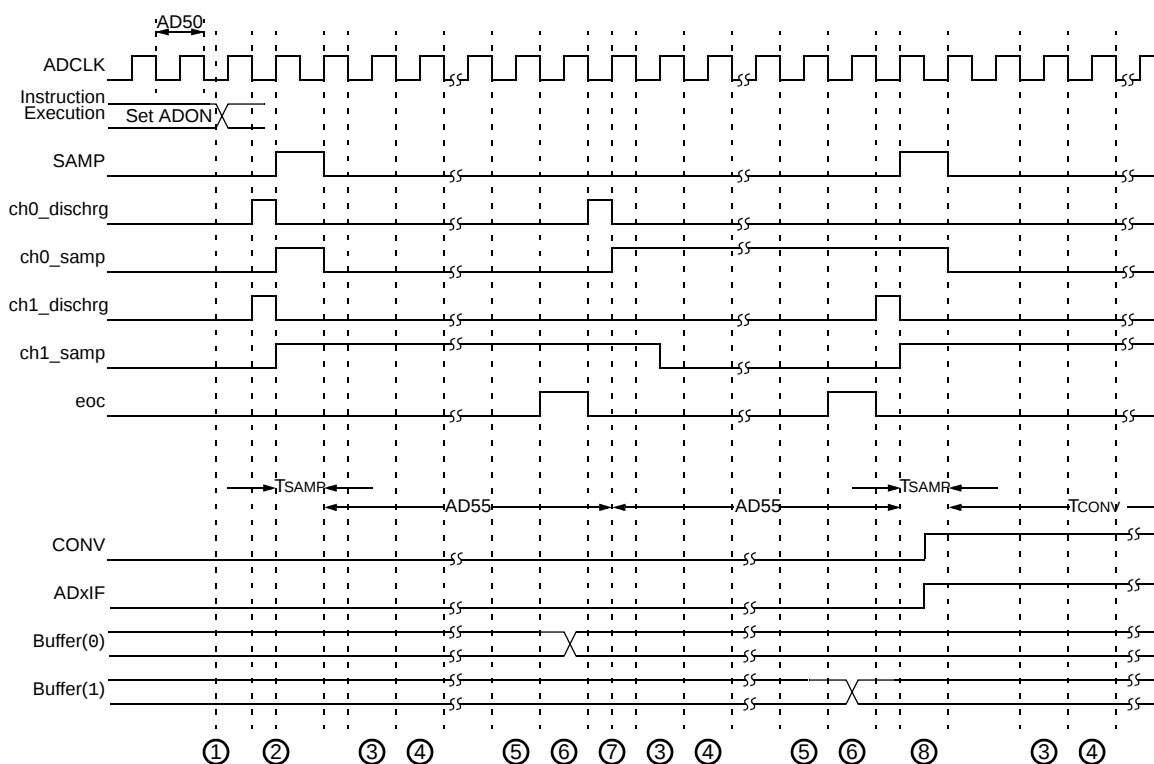
Note 1: These parameters are characterized, but not tested in manufacturing.

2: Because the sample caps will eventually lose charge, clock rates below 10 kHz can affect linearity performance, especially at elevated temperatures.

3: Characterized by design but not tested.

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FIGURE 29-19: ANALOG-TO-DIGITAL CONVERSION (10-BIT MODE) TIMING CHARACTERISTICS
(CHPS<1:0> = 01, SIMSAM = 0, ASAM = 1, SSRC<2:0> = 111, SAMC<4:0> = 00001)



- ① – Software sets ADxCON. ADON to start AD operation.
- ② – Sampling starts after discharge period. TSAMP is described in **Section 17. “10-bit Analog-to-Digital Converter (ADC)”** (DS61104) of the “PIC32 Family Reference Manual”.
- ③ – Convert bit 9.
- ④ – Convert bit 8.
- ⑤ – Convert bit 0.
- ⑥ – One TAD for end of conversion.
- ⑦ – Begin conversion of next channel.
- ⑧ – Sample for time specified by SAMC<4:0>.

FIGURE 29-23: EJTAG TIMING CHARACTERISTICS

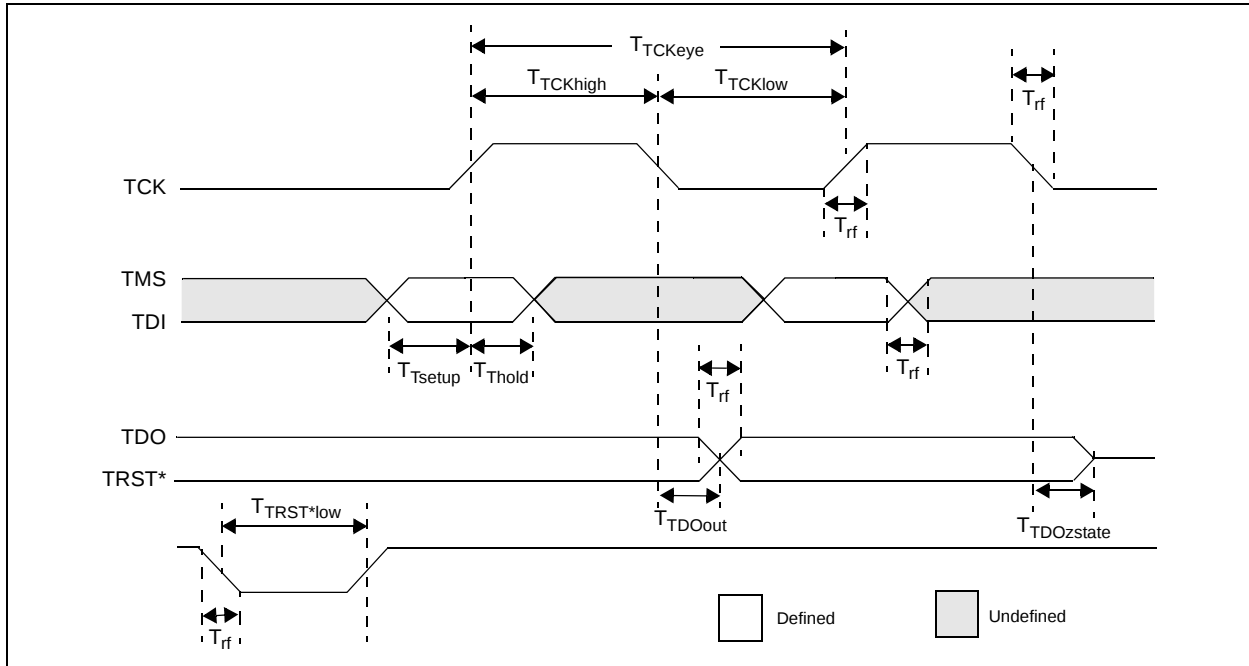


TABLE 29-41: EJTAG TIMING REQUIREMENTS

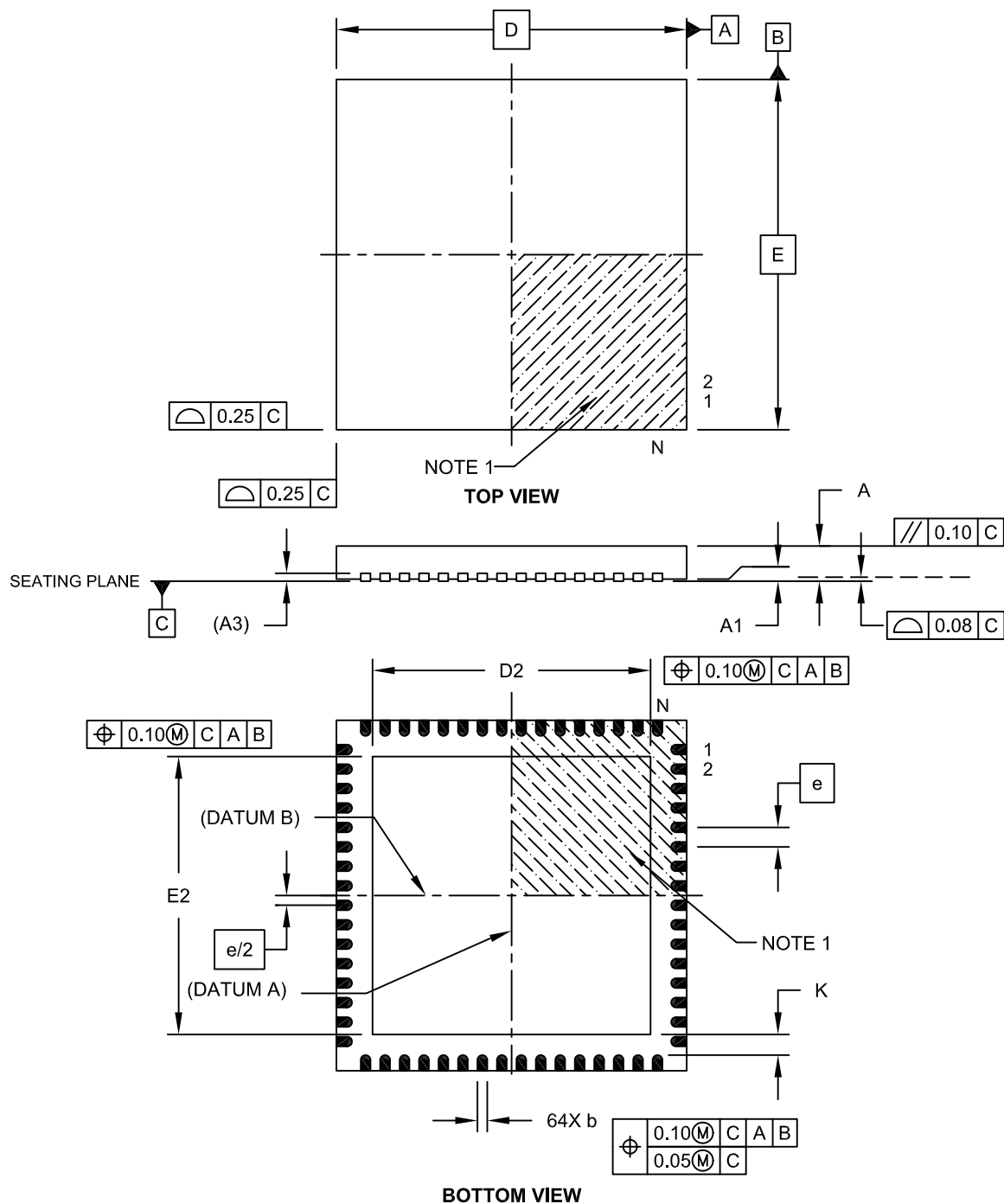
AC CHARACTERISTICS				Standard Operating Conditions: 2.3V to 3.6V (unless otherwise stated) Operating temperature -40°C ≤ TA ≤ +85°C for Industrial -40°C ≤ TA ≤ +105°C for V-Temp		
Param. No.	Symbol	Description ⁽¹⁾	Min.	Max.	Units	Conditions
EJ1	TTCKCYC	TCK Cycle Time	25	—	ns	—
EJ2	TTCKHIGH	TCK High Time	10	—	ns	—
EJ3	TTCKLOW	TCK Low Time	10	—	ns	—
EJ4	TTSETUP	TAP Signals Setup Time Before Rising TCK	5	—	ns	—
EJ5	TTHOLD	TAP Signals Hold Time After Rising TCK	3	—	ns	—
EJ6	TTDOOUT	TDO Output Delay Time from Falling TCK	—	5	ns	—
EJ7	TTDOZSTATE	TDO 3-State Delay Time from Falling TCK	—	5	ns	—
EJ8	TTRSTLOW	TRST Low Time	25	—	ns	—
EJ9	TRF	TAP Signals Rise/Fall Time, All Input and Output	—	—	ns	—

Note 1: These parameters are characterized, but not tested in manufacturing.

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64-Lead Plastic Quad Flat, No Lead Package (MR) – 9x9x0.9 mm Body [QFN] With 7.15 x 7.15 Exposed Pad [QFN]

Note: For the most current package drawings, please see the Microchip Packaging Specification located at <http://www.microchip.com/packaging>



Microchip Technology Drawing C04-149C Sheet 1 of 2